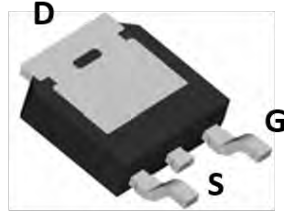
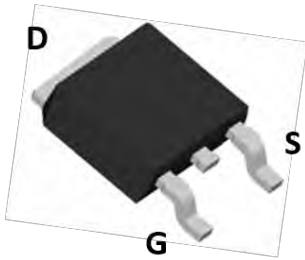
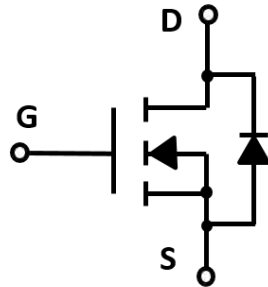


## N-Channel Enhancement Mode Field Effect Transistor



**TO-252**



### Product Summary

- $V_{DS}$  150V
- $I_D$  25A
- $R_{DS(ON)}$ ( at  $V_{GS}=10V$ ) <75 mohm
- $R_{DS(ON)}$ ( at  $V_{GS}=4.5V$ ) <88 mohm

### General Description

- Split Gate Trench MOSFET technology
- High Speed Power Switching, logic level
- Enhanced Body diode dv/dt capability
- Enhanced Avalanche Ruggedness
- 100% UIS Tested, 100% Rg Tested

### Applications

- Synchronous Rectification in SMPS
- Hard Switching and High Speed Circuit
- Power Tools
- UPS
- Motor Control

### ■ Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Maximum	Unit
Drain-source Voltage		$V_{DS}$	150	V
Gate-source Voltage		$V_{GS}$	$\pm 20$	V
Drain Current	$T_C=25^\circ\text{C}$	$I_D$	25	A
	$T_C=100^\circ\text{C}$		16	
Pulsed Drain Current <sup>A</sup>		$I_{DM}$	90	A
Avalanche Energy, Single Pulse <sup>B</sup>		$E_{AS}$	3.75	mJ
Total Power Dissipation @ $T_C=25^\circ\text{C}$		$P_D$	52	W
Thermal Resistance Junction-to-Case		$R_{\theta JC}$	2.4	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range		$T_J, T_{STG}$	-55~+150	$^\circ\text{C}$

### ■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
LMD25N15B	F2		2500	2500		13" reel

## ■ Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =250μA	150			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =150V, V <sub>GS</sub> =0V	T <sub>J</sub> =25°C		1	μA
			T <sub>J</sub> =100°C		100	
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> =0V			± 100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =250μA	1.0	2.0	3.0	V
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =5.0A		63	75	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =4.0A		70	88	
Trans conductance	g <sub>fs</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =15A		18		S
Gate Resistance	R <sub>G</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> Open, f=1MHZ		5.0		Ω
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =15.0A, V <sub>GS</sub> =0V		0.9	1.2	V
Maximum Body-Diode Continuous Current	I <sub>S</sub>				15.0	A
<b>Dynamic Parameters</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =75V, V <sub>GS</sub> =0V, f=1MHZ		625		pF
Output Capacitance	C <sub>oss</sub>			37		
Reverse Transfer Capacitance	C <sub>rss</sub>			13		
<b>Switching Parameters</b>						
Total Gate Charge (10V)	Q <sub>g</sub> (10V)	V <sub>GS</sub> =10V, V <sub>DD</sub> =75V, I <sub>D</sub> =5A		11.6		nC
Total Gate Charge (4.5V)	Q <sub>g</sub> (4.5V)			6.5		
Gate Source Charge	Q <sub>gs</sub>			1.2		
Gate Drain Charge	Q <sub>gd</sub>			4		
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>GS</sub> =10V, V <sub>DD</sub> =75V, I <sub>D</sub> =5A, R <sub>GEN</sub> =10Ω		10		ns
Turn-on Rise Time	t <sub>r</sub>			7		
Turn-off Delay Time	t <sub>d(off)</sub>			14		
Turn-off Fall Time	t <sub>f</sub>			3		
Reverse Recovery Time	t <sub>rr</sub>	V <sub>R</sub> =75V, I <sub>F</sub> =5A, dI <sub>F</sub> /dt=100A/μs		50		ns
Reverse Recovery Charge	Q <sub>rr</sub>			70		nC

A. Pulse Test: Pulse Width ≤ 300μs, Duty cycle ≤ 2%.

B. L=0.3mH, T<sub>A</sub> =25°C.

## ■ Typical Performance Characteristics

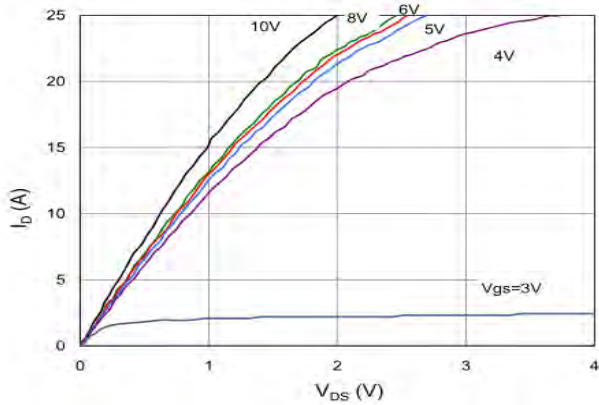


Figure1. Output Characteristics

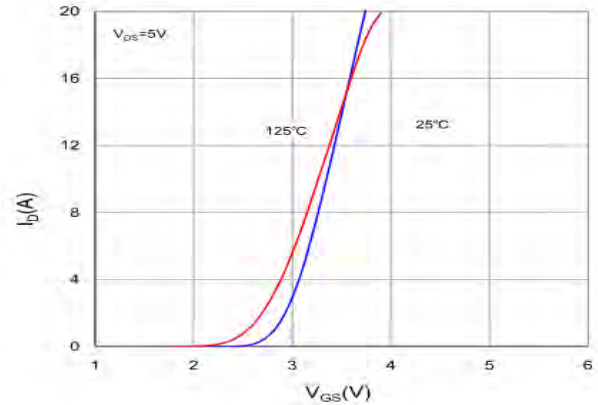


Figure2. Transfer Characteristics

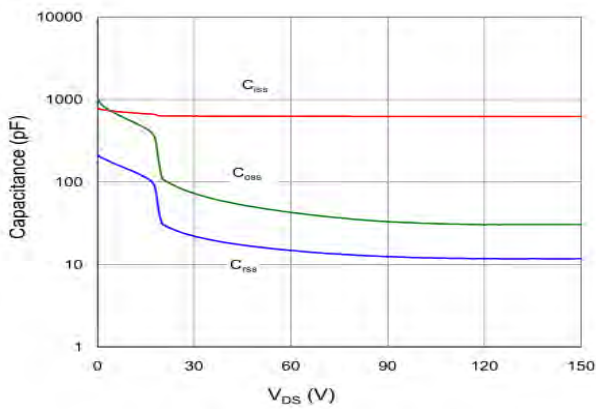


Figure3. Capacitance Characteristics

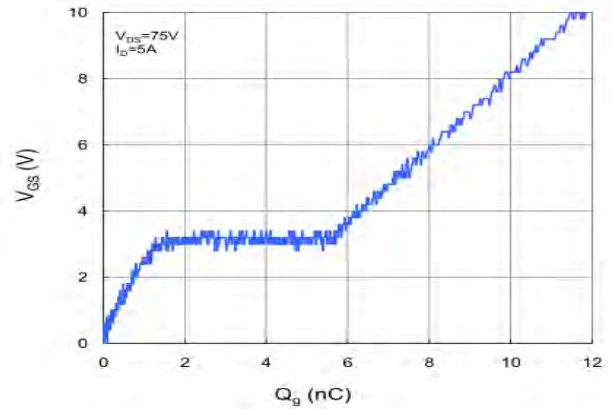


Figure4. Gate Charge

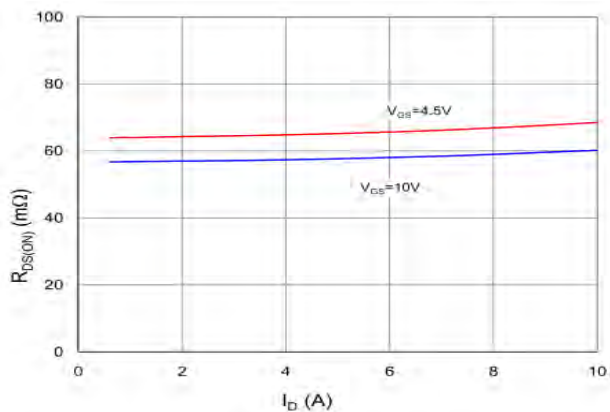


Figure5. Drain-Source on Resistance

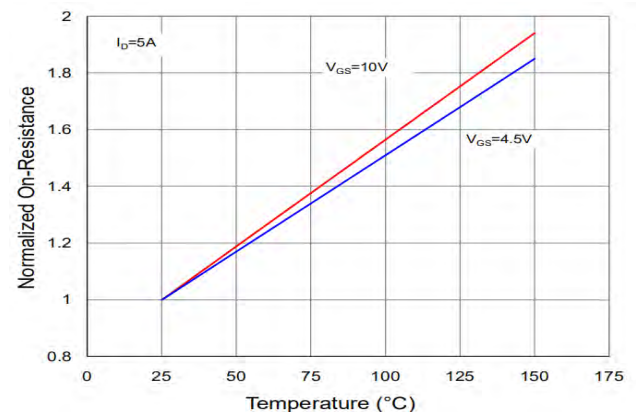


Figure6. Normalized On-Resistance vs. Junction Temperature

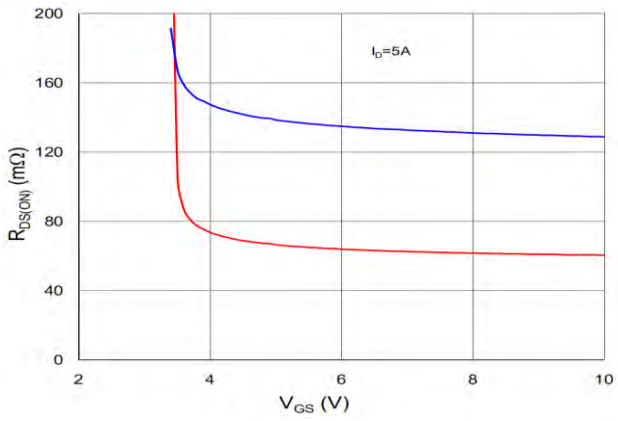


Figure7. On-Resistance vs. Gate-Source Voltage

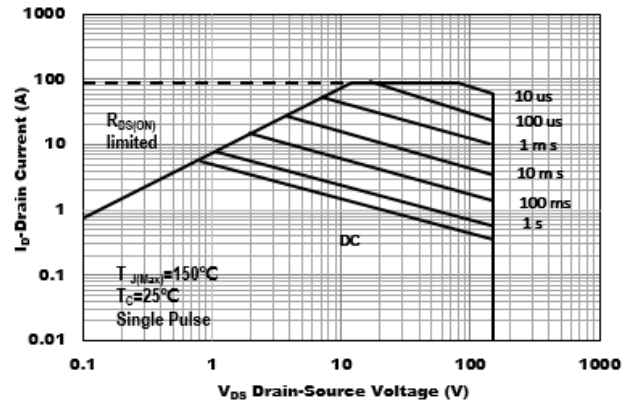


Figure8. Safe Operation Area

Figure A: Gate Charge Test Circuit & Waveforms

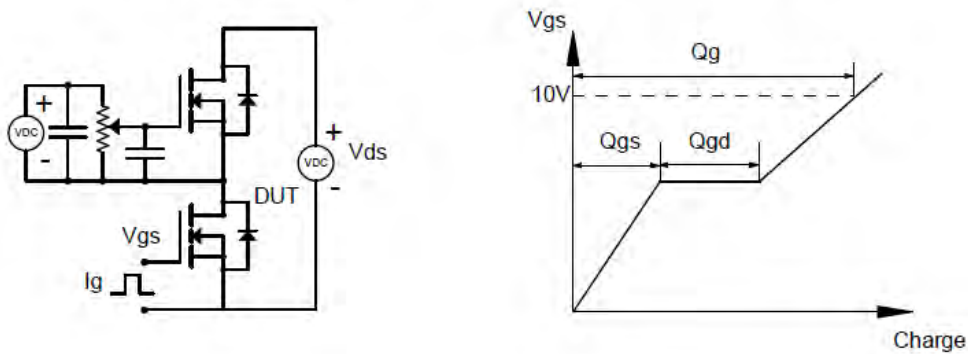


Figure B: Resistive Switching Test Circuit & Waveforms

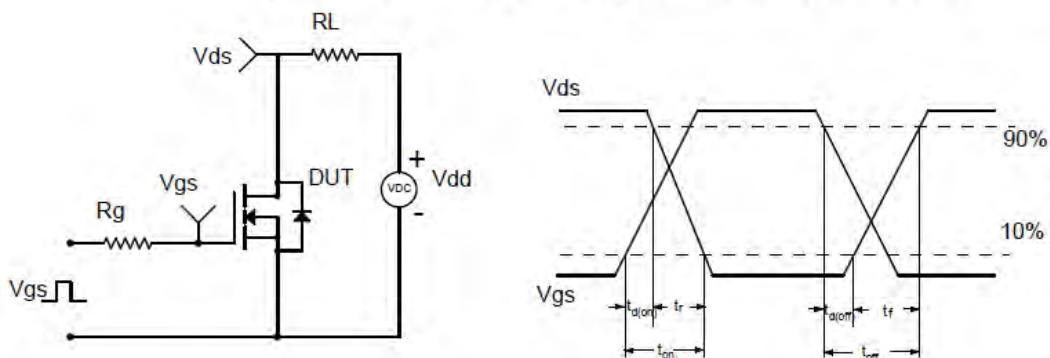


Figure C: Unclamped Inductive Switching (UIS) Test

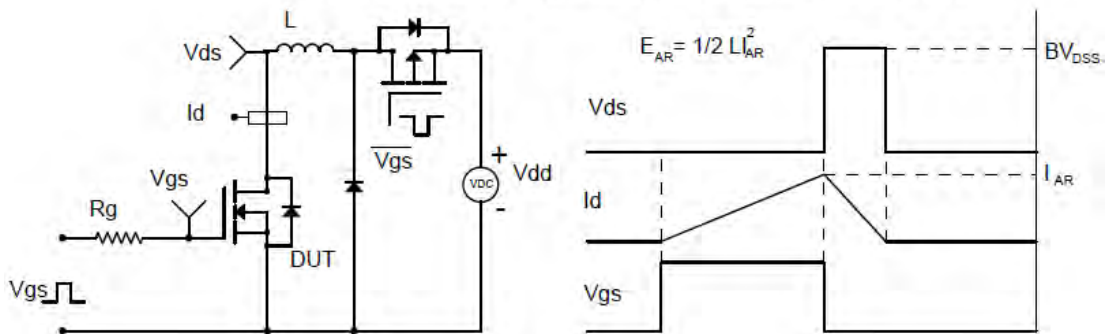
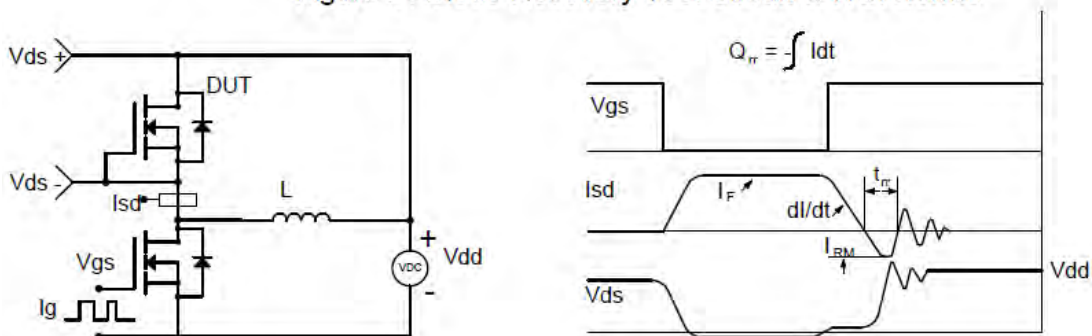
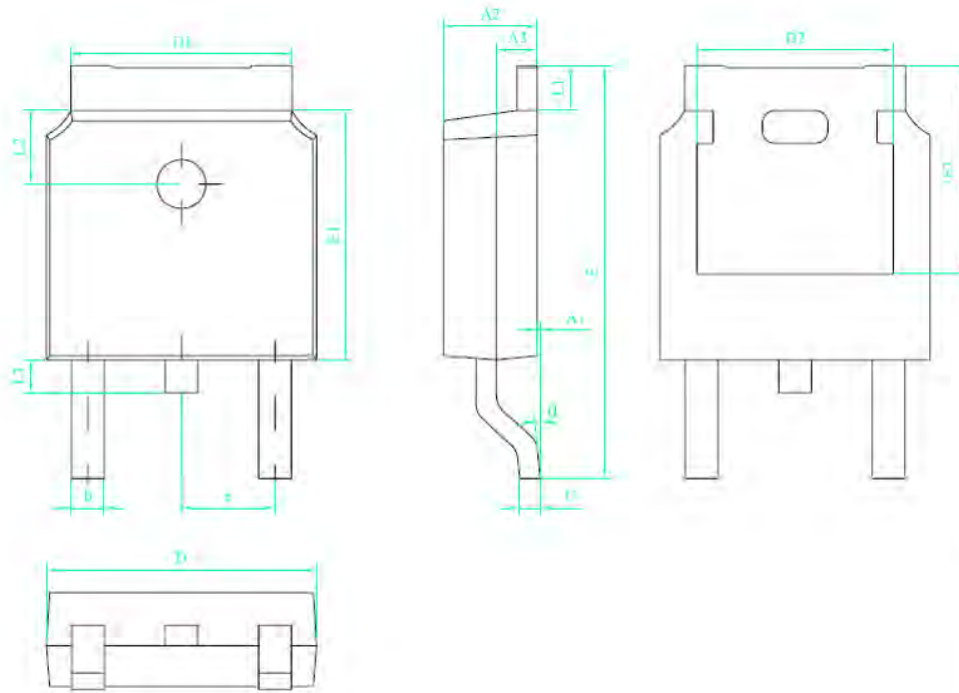


Figure D: Diode Recovery Test Circuit & Waveforms



## ■TO-252 Package information



符号	尺寸		
	min	nom	max
A1	0	—	0.10
A2	2.20	2.30	2.40
A3	0.90	1.00	1.10
b	0.75	—	0.85
c	0.50	—	0.60
D	6.50	6.60	6.70
D1	5.30	5.40	5.50
D2	4.70	4.80	4.90
E	9.90	10.10	10.30
E1	6.00	6.10	6.20
E2	5.20	5.30	5.40
c	2.20	2.286	2.40
L1	0.90	—	1.25
L2	1.70	1.80	1.90
L3	0.60	0.80	1.00
$\theta$	0°	—	8°

### 技术要求:

1. 树脂体不应有崩裂、缺损等缺陷;
2. 树脂上下部X、Y方向偏差不得超过0.20;
3. 胶体两端留胶总宽和宽度不得超过0.50;
4. 所有单位为mm;